



Hostaform® acetal copolymer grade S 9363 XAP®2 is an impact modified grade for demanding applications. Hostaform® S 9363 XAP®2 provides good impact strength while improving modulus and weld line strength over standard impact modified grades such as Hostaform® S 9063, and also exhibits exceptional low emission performance meeting or exceeding the requirements of many automotive markets. Chemical abbreviation according to ISO 1043-1: POM-HI ECO-B: Hostaform ECO-B is a POM-Copolymer with the same properties and performance as standard grades but produced with sustainability in mind. Using a mass-balance approach, biogenic feedstocks are used to offset the use of fossil-based raw materials and decrease greenhouse gas emissions. The process is audited and certified according to the ISCC Plus mass balance approach.

Product information

Product information			
Resin Identification	POM		ISO 1043
Part Marking Code	>POM<		ISO 11469
Rheological properties			
Melt volume-flow rate		cm ³ /10min	ISO 1133
Temperature	190		
Load	2.16	•	100 004 4 0577
Moulding shrinkage, parallel	1.8		ISO 294-4, 2577
Moulding shrinkage, normal	1.6	%	ISO 294-4, 2577
Typical mechanical properties			
Tensile modulus	2000	MPa	ISO 527-1/-2
Tensile stress at yield, 50mm/min		MPa	ISO 527-1/-2
Tensile strain at yield, 50mm/min	12		ISO 527-1/-2
Flexural modulus	2000		ISO 178
Charpy impact strength, 23°C		kJ/m² kJ/m²	ISO 179/1eU ISO 179/1eU
Charpy impact strength, -30°C Charpy notched impact strength, 23°C		kJ/m²	ISO 179/1e0 ISO 179/1eA
Charpy notched impact strength, -30°C		kJ/m ²	ISO 179/1eA
Izod notched impact strength, 23°C		kJ/m ²	ISO 180/1A
Izod notched impact strength, -40°C		kJ/m²	ISO 180/1A
Hardness, Rockwell, M-scale	65		ISO 2039-2
Poisson's ratio	0.4 ^[C]		
[C]: Calculated			
Thermal properties			
Melting temperature, 10°C/min	165	°C	ISO 11357-1/-3
Temperature of deflection under load, 1.8 MPa		°C	ISO 75-1/-2
Temperature of deflection under load, 0.45 MPa	148	°C	ISO 75-1/-2
Coefficient of linear thermal expansion	110	E-6/K	ISO 11359-1/-2
(CLTE), parallel	110	E-6/K	ISO 11359-1/-2
Coefficient of linear thermal expansion (CLTE), normal	110	E-0/N	130 11339-1/-2

Printed: 2025-05-30 Page: 1 of 6

Revised: 2024-12-03 Source: Celanese Materials Database





Physical/Other properties

Humidity absorption, 2mm	0.25 %	Sim. to ISO 62
Water absorption, 2mm	0.8 %	Sim. to ISO 62
Density	1380 kg/m ³	ISO 1183

Injection

Drying Recommended	no	
Drying Temperature	100	°C
Drying Time, Dehumidified Dryer	3 - 4	h
Processing Moisture Content	≤0.2	%
Melt Temperature Optimum	190	°C
Min. melt temperature	180	°C
Max. melt temperature	200	°C
Screw tangential speed	≤0.3	m/s
Mold Temperature Optimum	65	°C
Min. mould temperature	60	°C
Max. mould temperature	70	°C
Hold pressure range	60 - 120	MPa
Back pressure	2	MPa

Characteristics

Processing Injection Moulding, Extrusion

Delivery form Pellets

Additives Release agent

Special characteristics High impact or impact modified

Sustainability Bio-Content

Additional information

Processing Notes Pre-Drying

Drying is suggested to help achieve low emission performance and to counter if material has contacted moisture through improper storage and handling.

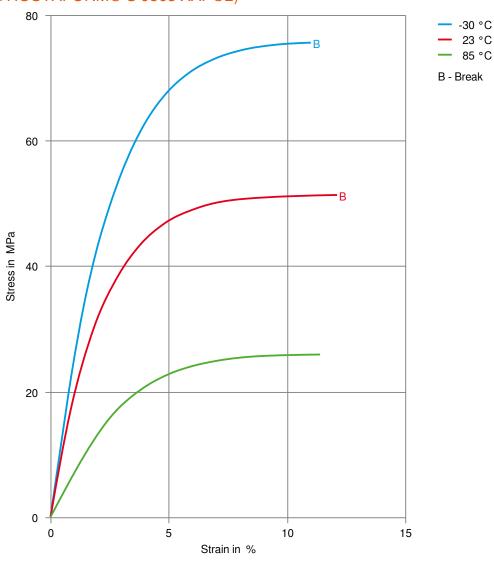
Printed: 2025-05-30 Page: 2 of 6

Revised: 2024-12-03 Source: Celanese Materials Database





Stress-strain (measured on HOSTAFORM® S 9363 XAP®2)

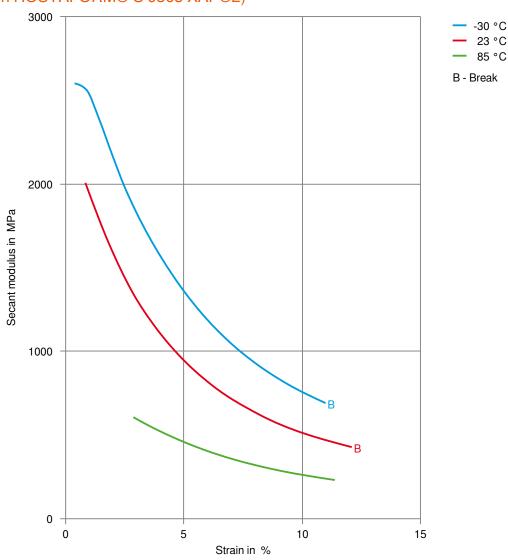


Printed: 2025-05-30 Page: 3 of 6





Secant modulus-strain (measured on HOSTAFORM® S 9363 XAP®2)



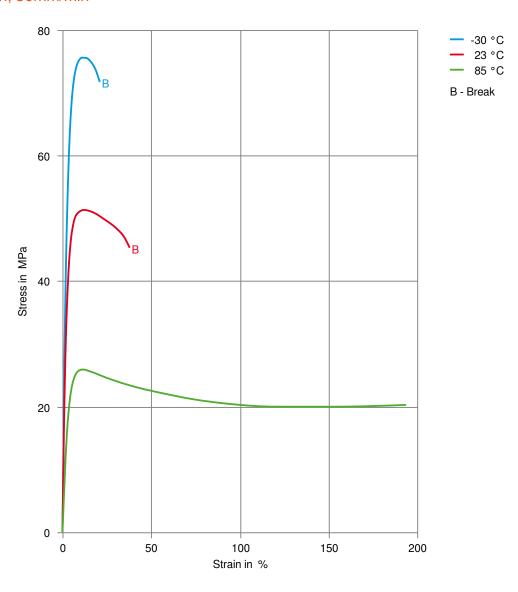
Printed: 2025-05-30 Page: 4 of 6

Revised: 2024-12-03 Source: Celanese Materials Database





Stress-strain, 50mm/min

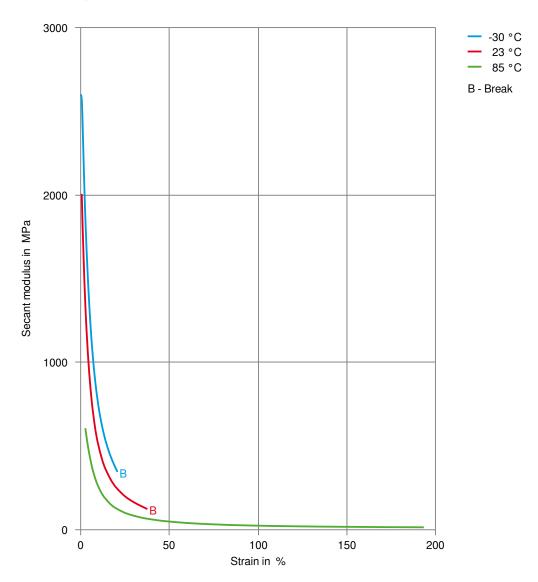


Printed: 2025-05-30 Page: 5 of 6





Secant modulus-strain, 50mm/min



Printed: 2025-05-30 Page: 6 of 6

Revised: 2024-12-03 Source: Celanese Materials Database

NOTICE TO USERS: Values shown are based on testing of laboratory test specimens and represent data that fall within the standard range of properties for natural material. These values alone do not represent a sufficient basis for any part design and are not intended for use in establishing maximum, minimum, or ranges of values for specification purposes. Colourants or other additives may cause significant variations in data values. Properties of moulded parts can be influenced by a wide variety of factors including, but not limited to, material selection, additives, part design, processing conditions and environmental exposure. Other than those products expressly identified as medical grade (including by MT® product designation or otherwise), Celanese's products are not intended for use in medical or dental implants. Regardless of any such product designation, any determination of the suitability of a particular material and part design for any use contemplated by the users and the manner of such use is the sole responsibility of the users, who must assure themselves that the material as subsequently processed meets the needs of their particular product or use. To the best of our knowledge, the information contained in this publication is accurate; however, we do not assume any liability whatsoever for the accuracy and completeness of such information. The information contained in this publication should not be construed as a promise or guarantee of specific properties of our products. It is the sole responsibility of the users to investigate whether any existing patents are infringed by the use of the materials mentioned in this publication. Moreover, there is a need to reduce human exposure to many materials to the lowest practical limits in view of possible adverse effects. To the extent that any hazards may have been mentioned in this publication, we neither suggest nor guarantee that such hazards are the only ones that exist. We recommend that persons intending to rely on any recommendation or to use any e

© 2025 Celanese or its affiliates. All rights reserved. Celanese®, registered C-ball design and all other trademarks identified herein with ®, TM, SM, unless otherwise noted, are trademarks of Celanese or its affiliates. Fortron is a registered trademark of Fortron Industries LLC.